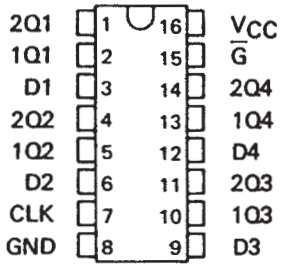
- Parallel Access
- Typical Propagation Delay Time . . . 20 ns
- Typical Power Dissipation . . . 120 mW
- Applications:
  - N-Bit Storage Files
  - Hex/BCD Serial-To-Parallel Converters

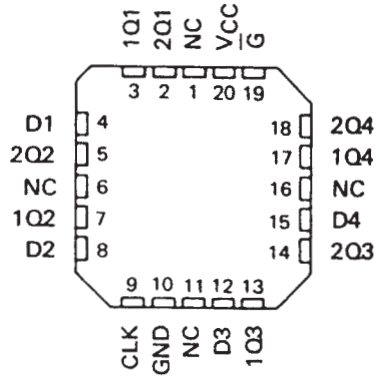
description

These octal registers are organized as two 4-bit bytes of storage. Upon application of a positive-going clock signal, the information stored in byte 1 is transferred into byte 2 as a new 4-bit byte is loaded into the byte 1 location via the four data lines. The full 8-bit word is available at the outputs after two clock cycles. Both the clock and the strobe lines are fully buffered.

SN54LS396 . . . J OR W PACKAGE
SN74LS396 . . . D OR N PACKAGE
(TOP VIEW)

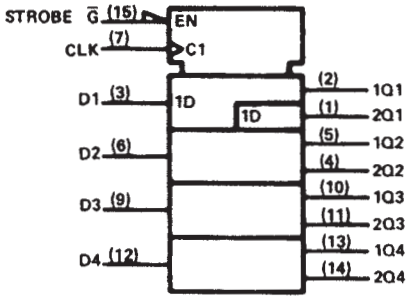


SN54LS396 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

logic symbol†



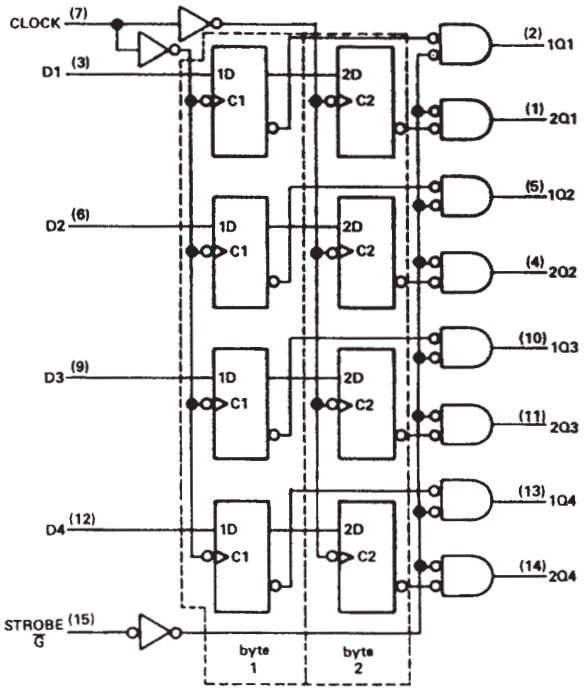
†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

FUNCTION TABLE

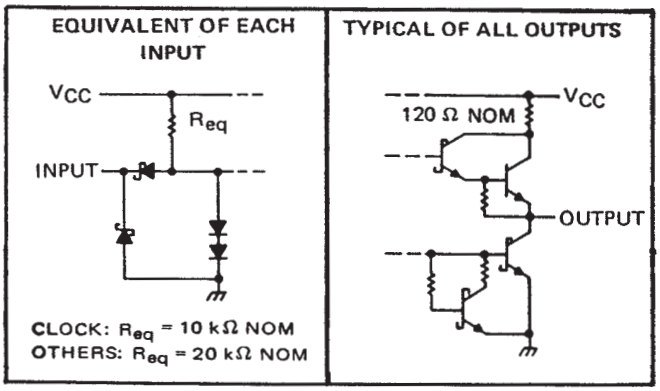
INPUTS						OUTPUTS							
STROBE $\overline{G}$	CLOCK	DATA				BYTE 1				BYTE 2			
		D1	D2	D3	D4	1Q1	1Q2	1Q3	1Q4	2Q1	2Q2	2Q3	2Q4
H	X	X	X	X	X	L	L	L	L	L	L	L	L
L	↑	a	b	c	d	a	b	c	d	$1Q1_n$	$1Q2_n$	$1Q3_n$	$1Q4_n$

H = high level (steady state), L = low level (steady state), X = irrelevant (any input, including transitions)
↑ = transition from low to high level
$1Q1_n$, $1Q2_n$, $1Q3_n$, $1Q4_n$ = the level of 1Q1, 1Q2, 1Q3, and 1Q4, respectively, before the most recent ↑ transition of the clock.

logic diagram (positive logic)



schematics of inputs and outputs



Pin numbers shown are for D, J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS396 . . . . . −55°C to 125°C
SN74LS396 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54LS396			SN74LS396			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−400			−400	μA
Low-level output current, I_{OL}			4			8	mA
Clock frequency, f_{clock}	0		30	0		30	MHz
Width of clock pulse, t_w	20			20			ns
Setup time, t_{su}	20			20			ns
Hold time, t_h	5			5			ns
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS396			SN74LS396			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.7			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN,	I_I = −18 mA			−1.5			−1.5	V
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IL} = MAX,	V_{IH} = 2 V, I_{OH} = −400 μA	2.5	3.4		2.7	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 8 mA					0.35	0.5	
I_I	Input current at maximum input voltage	Clock input	V_{CC} = MAX,	V_I = 7 V			0.2			0.2	mA
		Other inputs					0.1			0.1	
I_{IH}	High-level input current	Clock input	V_{CC} = MAX,	V_I = 2.7 V			40			40	μA
		Other inputs					20			20	
I_{IL}	Low-level input current	Clock input	V_{CC} = MAX,	V_I = 0.4 V			−0.8			−0.8	mA
		Other inputs					−0.4			−0.4	
I_{OS}	Short-circuit output current§		V_{CC} = MAX		−20		−100	−20		−100	mA
I_{CC}	Supply current		V_{CC} = MAX,	See Note 2		24	40		24	40	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
NOTE 2: I_{CC} is measured with 4.5 V applied to all inputs and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output from clock	C_L = 15 pF, R_L = 2 kΩ, See Note 3		20	30	ns
t_{PHL}	Propagation delay time, high-to-low-level output from clock			20	30	
t_{PLH}	Propagation delay time, low-to-high-level output from strobe			20	30	ns
t_{PHL}	Propagation delay time, high-to-low-level output from strobe			20	30	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
5962-9050301EA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS396J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS396J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS396DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74LS396DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74LS396N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS396N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SNJ54LS396J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54LS396J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

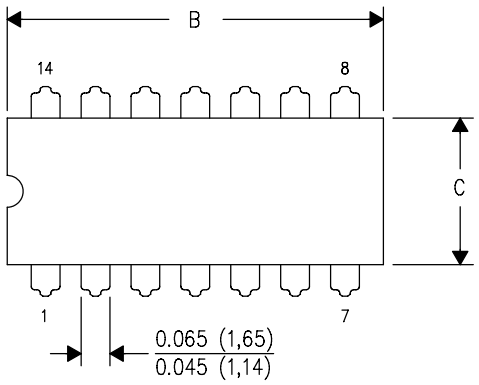
[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

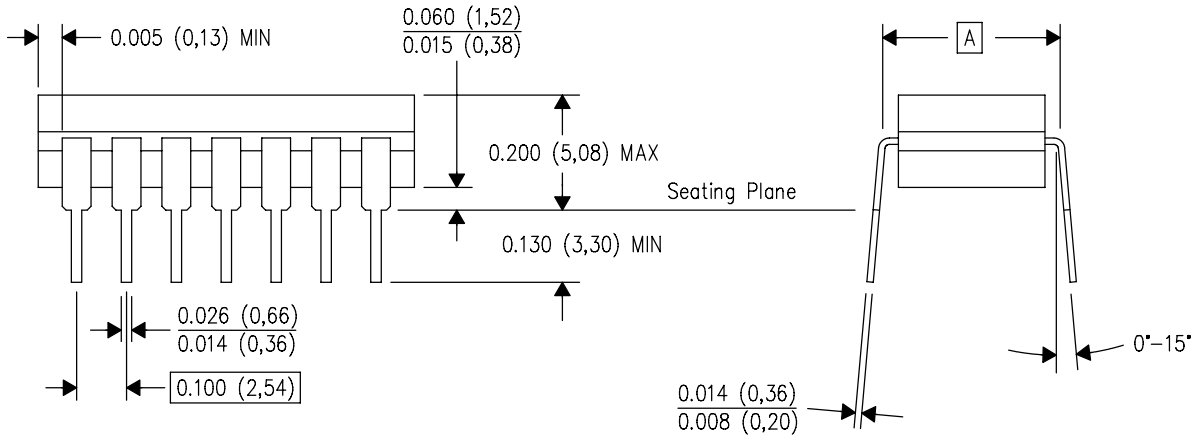
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



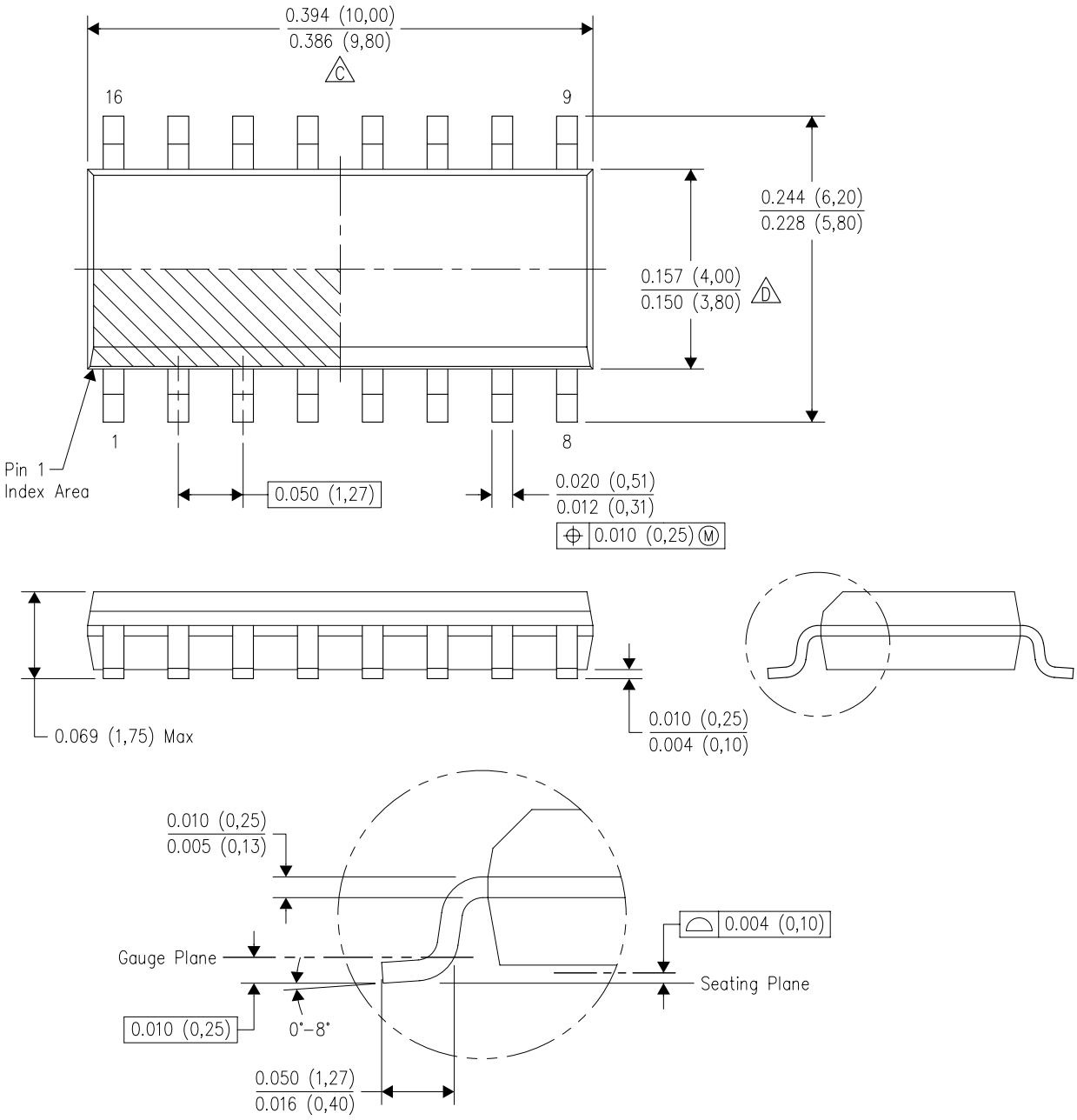
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE

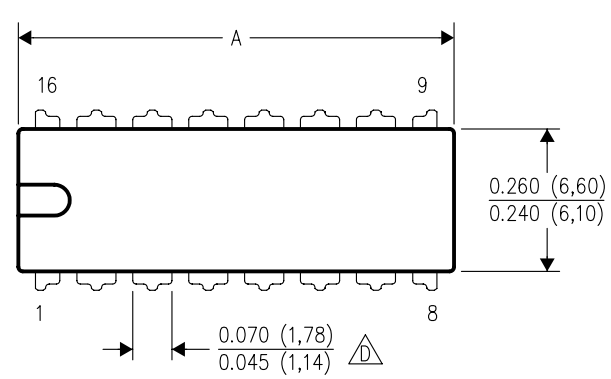


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AC.

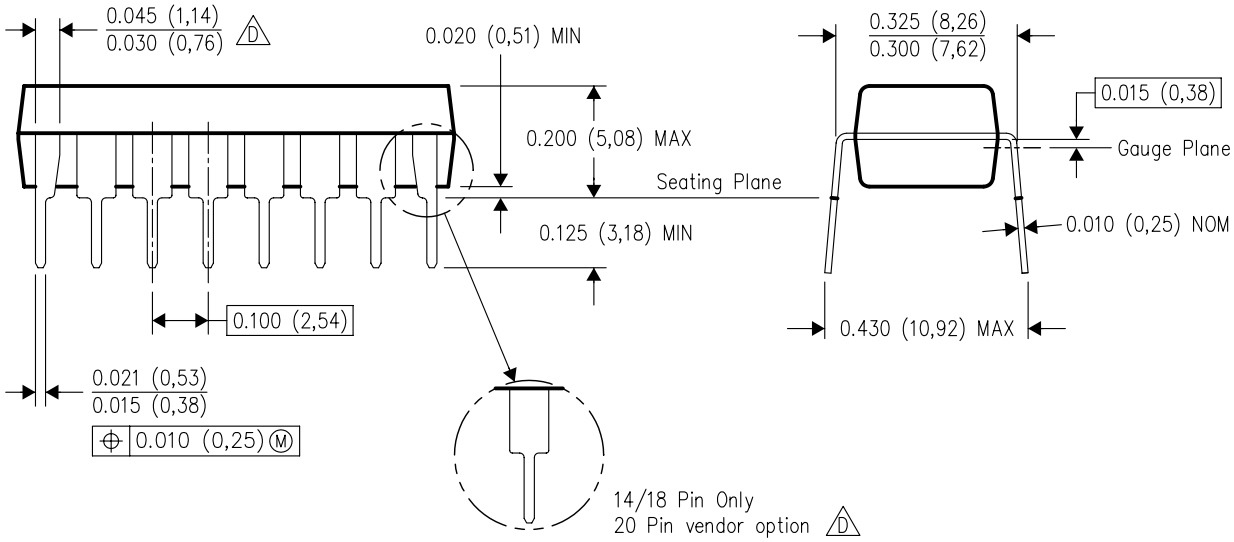
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
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SN54LS396J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS396J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS396DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
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SN74LS396N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS396N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SNJ54LS396J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54LS396J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI

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[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
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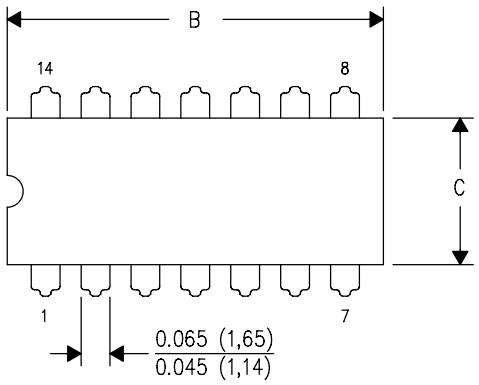
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

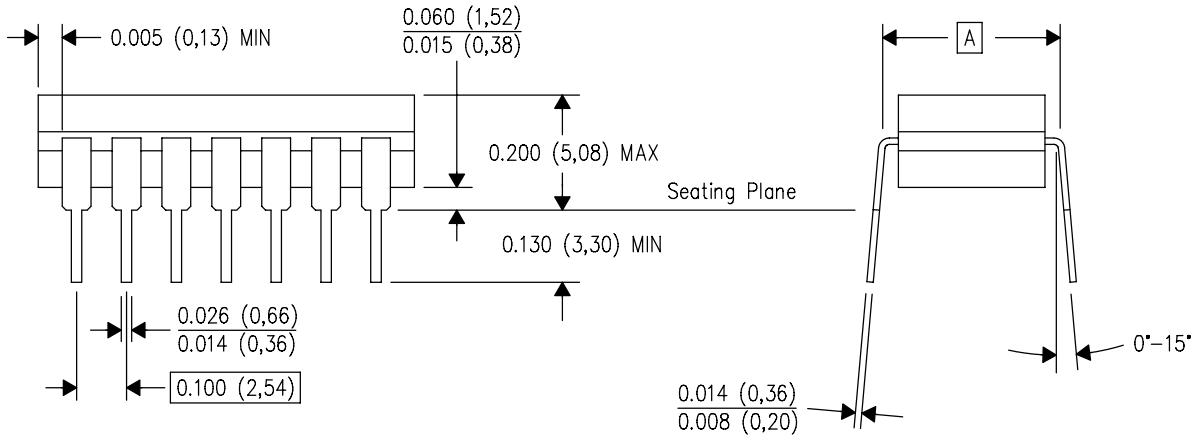
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
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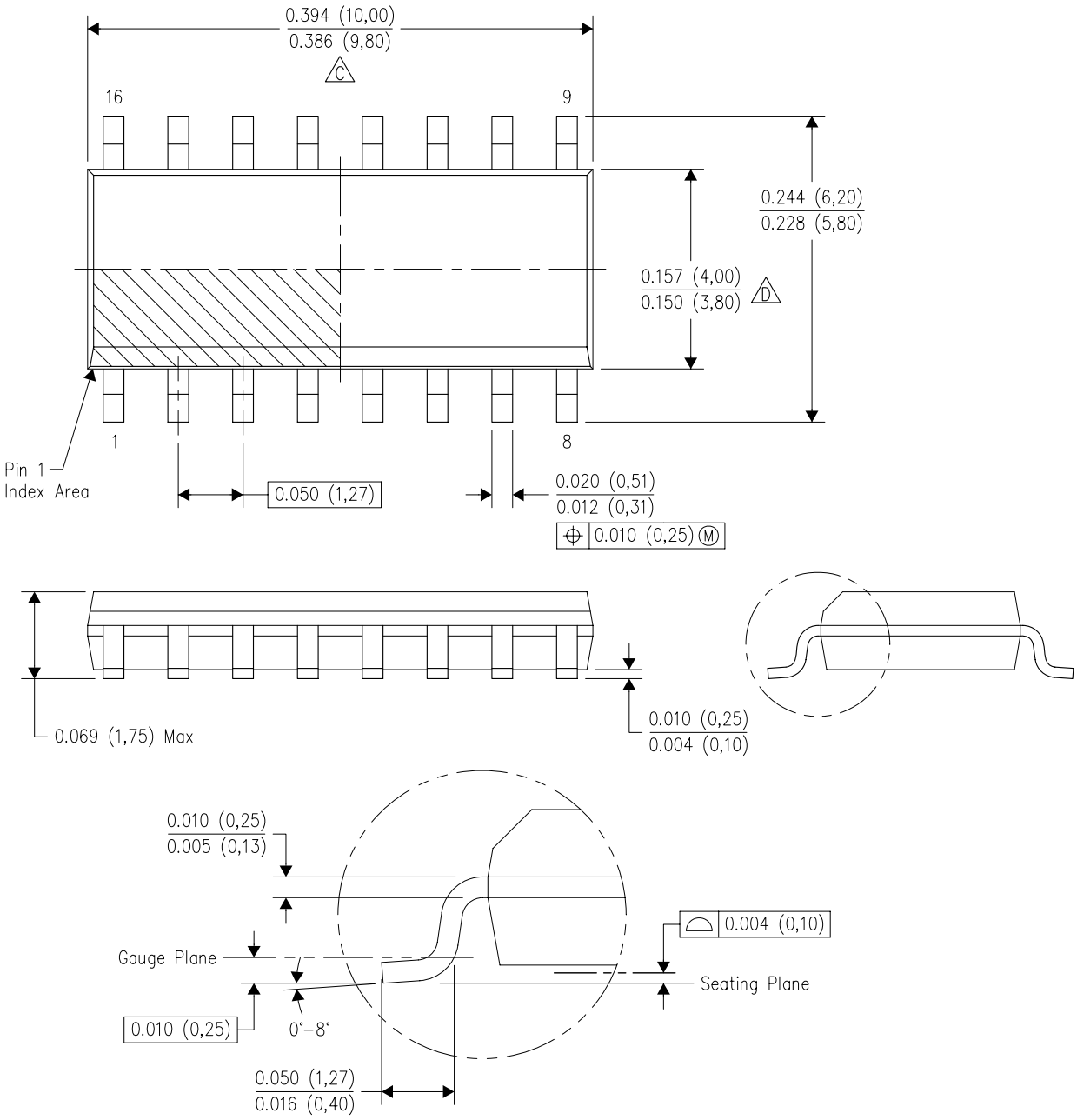
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE



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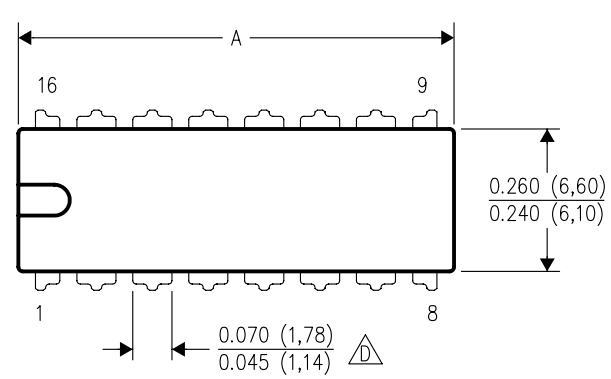
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AC.

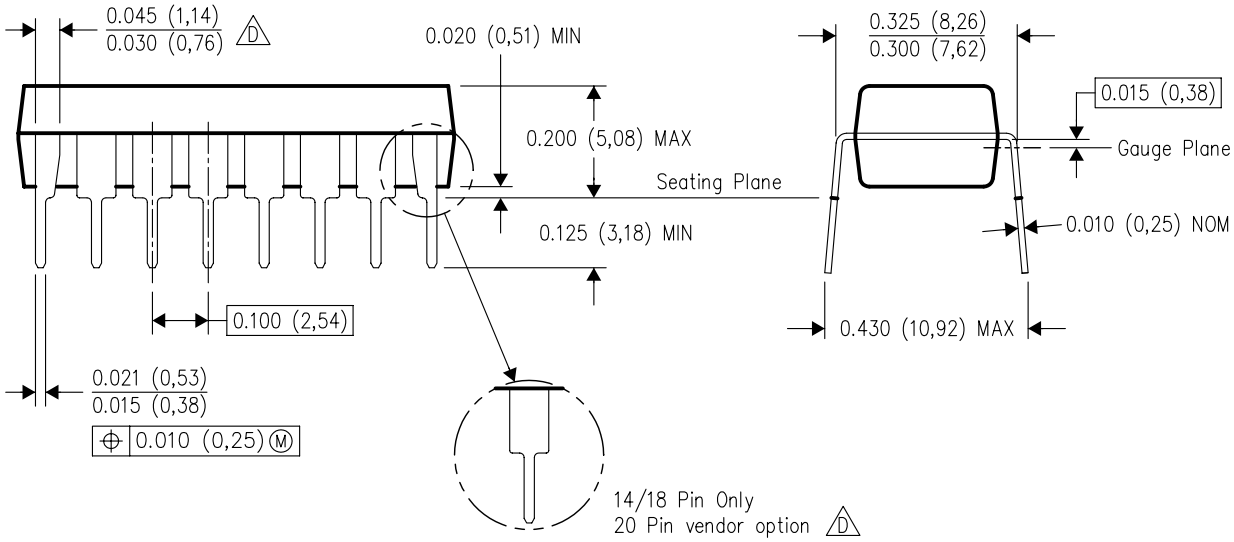
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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